**Vishay Semiconductors** 

## High Speed Infrared Emitting Diodes, 940 nm, Surface Emitter Technology

VSMY2940RG

www.vishay.com



### DESCRIPTION

As part of the SurfLight<sup>TM</sup> portfolio, the VSMY2940 series are infrared, 940 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

### **APPLICATIONS**

- Miniature light barrier
- Photointerrupters
- · Optical switch
- Emitter source for proximity sensors

### **FEATURES**

- Package type: surface-mount
- · Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- Peak wavelength: λ<sub>p</sub> = 940 nm
- · High reliability
- High radiant power
- · Very high radiant intensity
- Angle of half intensity:  $\varphi = \pm 10^{\circ}$
- · Suitable for high pulse current operation
- · Terminal configurations: gullwing or reverse gullwing
- Package matches with detector VEMD2000X01 series
- Floor life: 4 weeks, MSL 2a, according to J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

PRODUCT SUMMARY					
COMPONENT	l <sub>e</sub> (mW/sr)	φ <b>(deg)</b>	λ <sub>P</sub> (nm)	t <sub>r</sub> (ns)	
VSMY2940RG	145	± 10	940	10	
VSMY2940G	145	± 10	940	10	

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VSMY2940RG	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing	
VSMY2940G	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing	

Note

MOQ: minimum order quantity



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ABSOLUTE MAXIMUM RATINGS (T <sub>amb</sub> = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V <sub>R</sub>	5	V
Forward current		I <sub>F</sub>	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100 \ \mu s$	I <sub>FM</sub>	200	mA
Surge forward current	t <sub>p</sub> = 100 μs	I <sub>FSM</sub>	1	A
Power dissipation		Pv	180	mW
Junction temperature		Tj	100	°C
Operating temperature range		T <sub>amb</sub>	-40 to +85	°C
Storage temperature range		T <sub>stg</sub>	-40 to +100	°C
Soldering temperature	According to Fig. 10, J-STD-020	T <sub>sd</sub>	260	°C
Thermal resistance junction-to-ambient	J-STD-051, soldered on PCB	R <sub>thJA</sub>	250	K/W

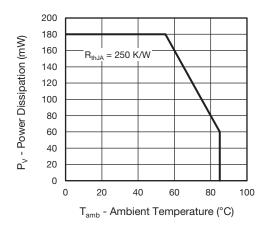


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

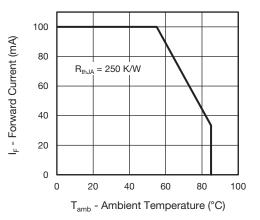


Fig. 2 - Forward Current Limit vs. Ambient Temperature

<b>BASIC CHARACTERISTICS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	V <sub>F</sub>	-	1.4	1.8	V
Forward voltage	$I_F = 1 \text{ A}, t_p = 100 \ \mu \text{s}$	V <sub>F</sub>	-	2.5	-	V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 100 mA	TK <sub>VF</sub>	-	-0.7	-	mV/K
Reverse current		I <sub>R</sub>	Not designed for reverse operation µA		μA	
Junction capacitance	$V_{R} = 0 V, f = 1 MHz, E = 0 mW/cm^{2}$	CJ	-	55	-	pF
Padiant intensity	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	l <sub>e</sub>	75	145	215	mW/sr
Radiant intensity	$I_F = 1 \text{ A}, t_p = 100 \ \mu \text{s}$	l <sub>e</sub>	-	1000	-	mW/sr
Radiant power	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	фе	-	55	-	mW
Temperature coefficient of radiant power	I <sub>F</sub> = 100 mA	TK¢ <sub>e</sub>	-	-0.2	-	%/K
Angle of half intensity		φ	-	± 10	-	deg
Peak wavelength	I <sub>F</sub> = 100 mA	λ <sub>p</sub>	920	940	960	nm
Spectral bandwidth	I <sub>F</sub> = 100 mA	Δλ	-	50	-	nm
Temperature coefficient of $\lambda_p$	I <sub>F</sub> = 100 mA	ΤΚλ <sub>p</sub>	-	0.25	-	nm/K
Rise time	I <sub>F</sub> = 100 mA, 10 % to 90 %	t <sub>r</sub>	-	10	-	ns
Fall time	I <sub>F</sub> = 100 mA, 10 % to 90 %	t <sub>f</sub>	-	10	-	ns

Rev. 1.1, 08-Dec-17

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### BASIC CHARACTERISTICS (Tamb = 25 °C, unless otherwise specified)

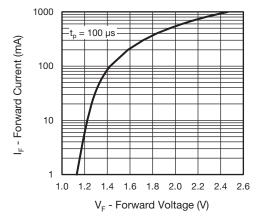


Fig. 3 - Forward Current vs. Forward Voltage

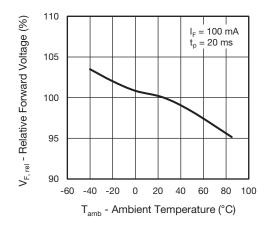


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

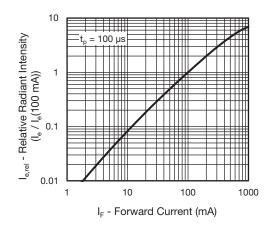


Fig. 5 - Relative Radiant Intensity vs. Forward Current

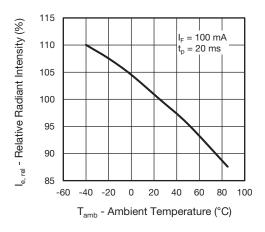


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

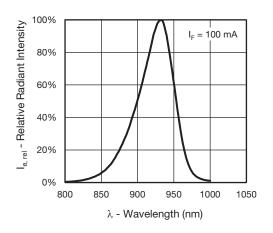


Fig. 7 - Relative Radiant Intensity vs. Wavelength

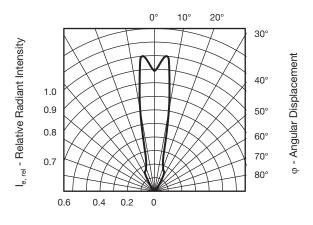


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

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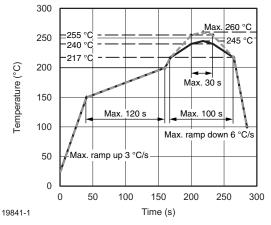
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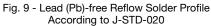
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## VSMY2940RG, VSMY2940G

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### SOLDER PROFILE





#### DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

### FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions:  $T_{amb} < 30\ ^\circ C,\ RH < 60\ \%$ 

Moisture sensitivity level 2a, according to J-STD-020.

#### DRYING

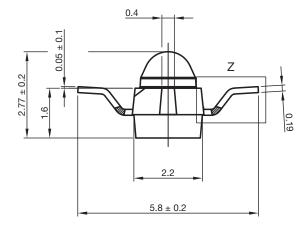
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

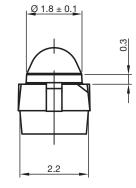


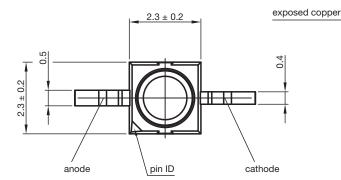


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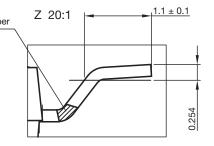
#### PACKAGE DIMENSIONS in millimeters: VSMY2940RG





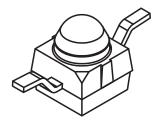


6.7





Not indicated tolerances  $\pm 0.1$ 



Drawing-No.: 6.544-5391.03-4 Issue: 2; 19.09.14

1.7

0.75

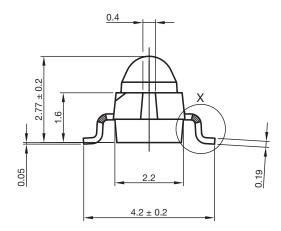
solder pad proposal acc. IPC 7351

Ø 2.3 ± 0.1

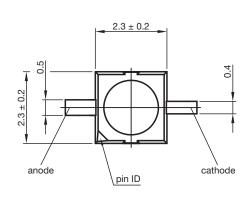
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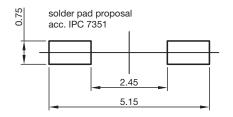


### PACKAGE DIMENSIONS in millimeters: VSMY2940G

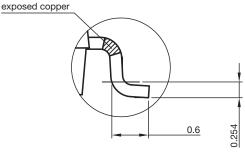


X 20:1



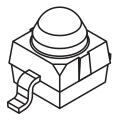


Drawing-No.: 6.544-5383.03-4 Issue: 2; 19.09.14





Not indicated tolerances  $\pm 0.1$ 

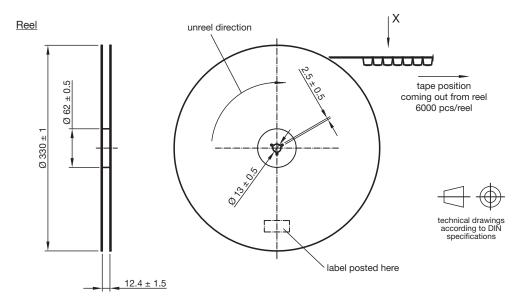


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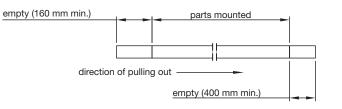


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### TAPING AND REEL DIMENSIONS in millimeters: VSMY2940RG



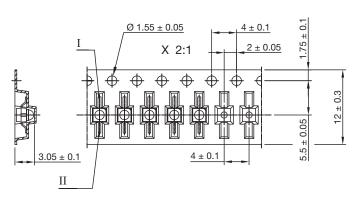
Leader and trailer tape



Terminal position in tape

Device	Lead I	Lead II
VEMT2000	Collector	Fmitter
VEMT2500	Collector	Emitter
VEMD2000		
VEMD2500		
VSMB2000	Cathode	Anode
VSMG2000		
VSMF2890RG		
VSMY2850RG	Anode	Cathode
VSMY2940RG	Anoue	Callloue

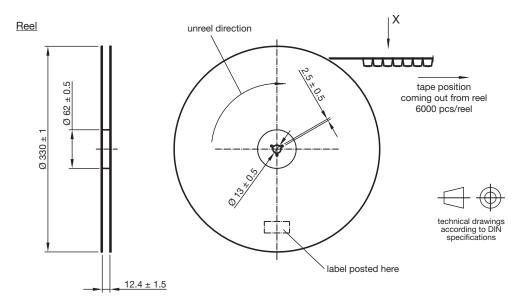
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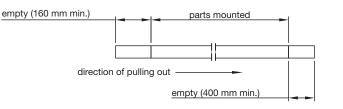
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### TAPING AND REEL DIMENSIONS in millimeters: VSMY2940G



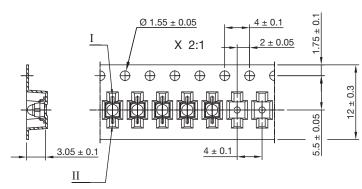
Leader and trailer tape

Terminal position in tape



Device Lead I Lead II VSMB2020 VSMG2020 VEMD2020 Cathode Anode VEMD2520 VSMF2890G VEMT2020 Collector Emitter VEMT2520 VSMY2850G Cathode Anode VSMY2940G







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